

LAT Planning Meeting

Mechanical/Thermal Systems February 16, 2005 Marc Campell



Status Feb. 15, 2005

SLAC

- Bonding of the Grid Top Flange Heat Pipes complete.
- Bonding of Grid Thermistors 50% complete.
- Grid bake-out compete (outgassing concern)
- Preparations for sell to I&T are underway



Status Feb. 15, 2005 (cont)

Lockheed Martin

- Received final Estimate at Completion from LM
 - Cost control measures required
 - De-scope options under evaluation.
- Received X-LAT plate (detail) from Vendor.
- End Item Data Review successfully held for X-LAT Heat Pipes.
 - Ready to bond into next assembly.
- X-LAT tool try completed.
 - Some minor modifications required to improve functionality of the tool. In work.
- Radiator panels potting of inserts and spools is 25% complete.
- Radiator panel repair techniques (for honeycomb bonding)
 have been developed and demonstrated. Ready to implement
 on flight units.

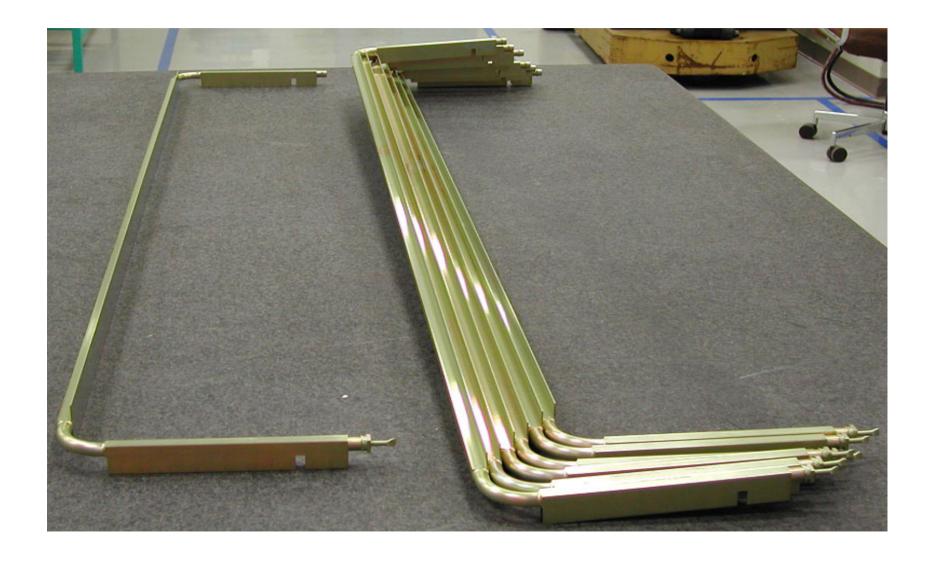


Grid Heat Pipe Bonding



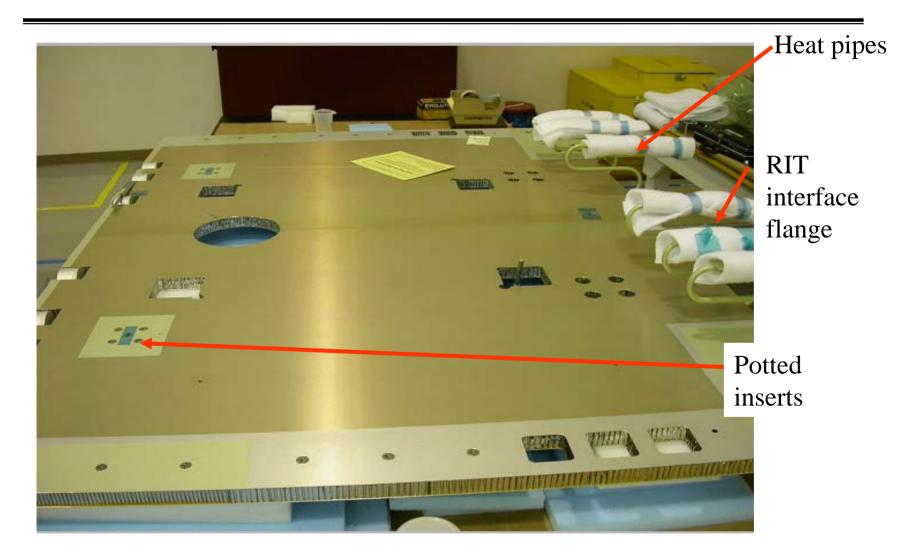


X-LAT Heat Pipes



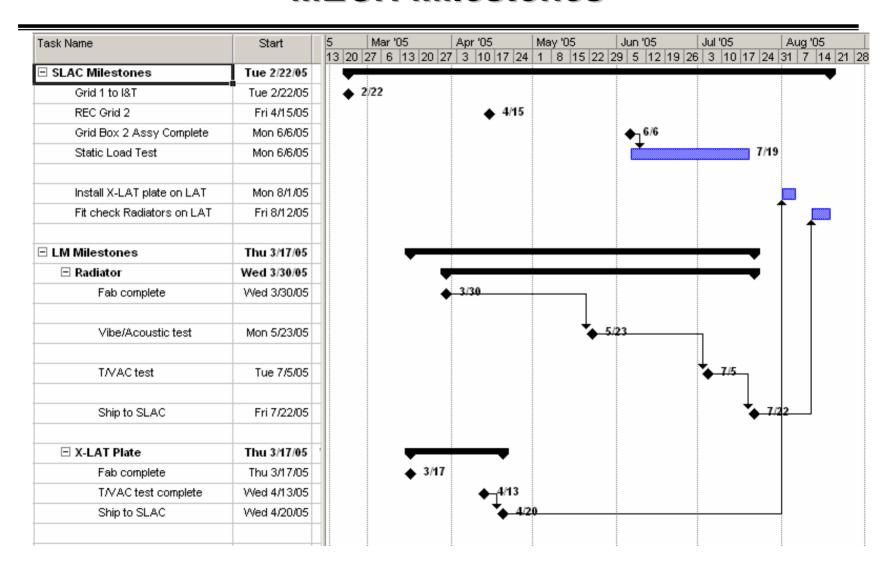


-Y Radiator Panel





MECH Milestones





Threats to RFI

- LM X-LAT & Radiator delivery have no float and LM manufacturing is not maintaining their schedule
- Radiator
 - First time use of bonding/assembly tool & procedures.
 There have been Discrepancies at each step along the way.
 MFG schedule and marching army costs.
 - Potential cost over runs in testing
 - Vibration/Acoustic tests
 - Fixture design
 - Instrumentation requirements
 - Timely resolution of test anomalies.